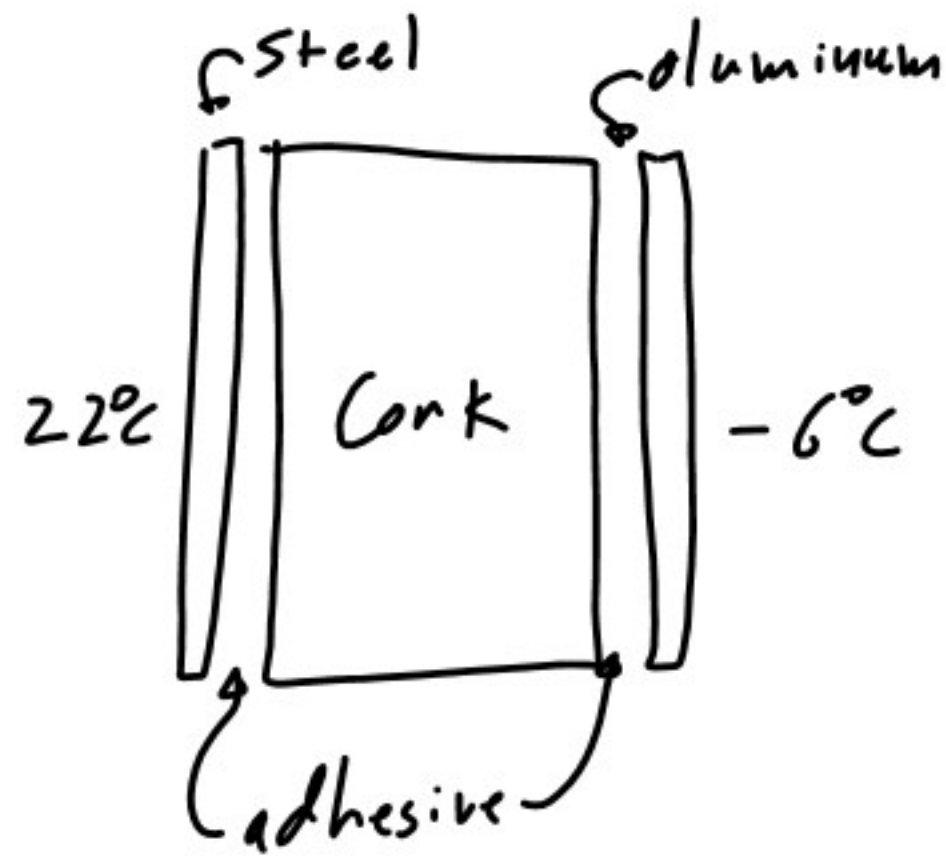


3.24 A commercial grade cubical freezer, 3 m on a side, has a composite wall consisting of an exterior sheet of 6.35-mm-thick plain carbon steel, an intermediate layer of 100-mm-thick cork insulation, and an inner sheet of 6.35-mm-thick aluminum alloy (2024). Adhesive interfaces between the insulation and the metallic strips are each characterized by a thermal contact resistance of $R''_{t,c} = 2.5 \times 10^{-4} \text{ m}^2 \cdot \text{K/W}$. What is the steady-state cooling load that must be maintained by the refrigerator under conditions for which the outer and inner surface temperatures are 22°C and -6°C , respectively?



$$R_{tot} = \frac{L_s}{k_s} + 2R''_{t,c} + \frac{L_c}{k_c} + \frac{L_a}{k_a}$$



$$L_s = L_a = 6.35 \text{ mm}$$

$$L_c = 100 \text{ mm}$$

$$K_a = 177 \frac{\text{W}}{\text{m K}}$$

$$K_c = 0.039 \frac{\text{W}}{\text{m K}}$$

$$K_s = 60.5 \frac{\text{W}}{\text{m K}}$$

$$R_{\text{tot}}'' = \frac{L_s}{K_s} + 2R_{tc}'' + \frac{L_c}{K_c} + \frac{L_a}{K_a}$$

$$= \frac{0.00635 \text{ m}}{60.5 \frac{\text{W}}{\text{m K}}} + 2 \cdot 2.5 \times 10^{-9} \frac{\text{m}^2 \text{K}}{\text{W}} + \frac{0.1 \text{ m}}{0.039 \frac{\text{W}}{\text{m K}}} + \frac{0.00635 \text{ m}}{177 \frac{\text{W}}{\text{m K}}}$$

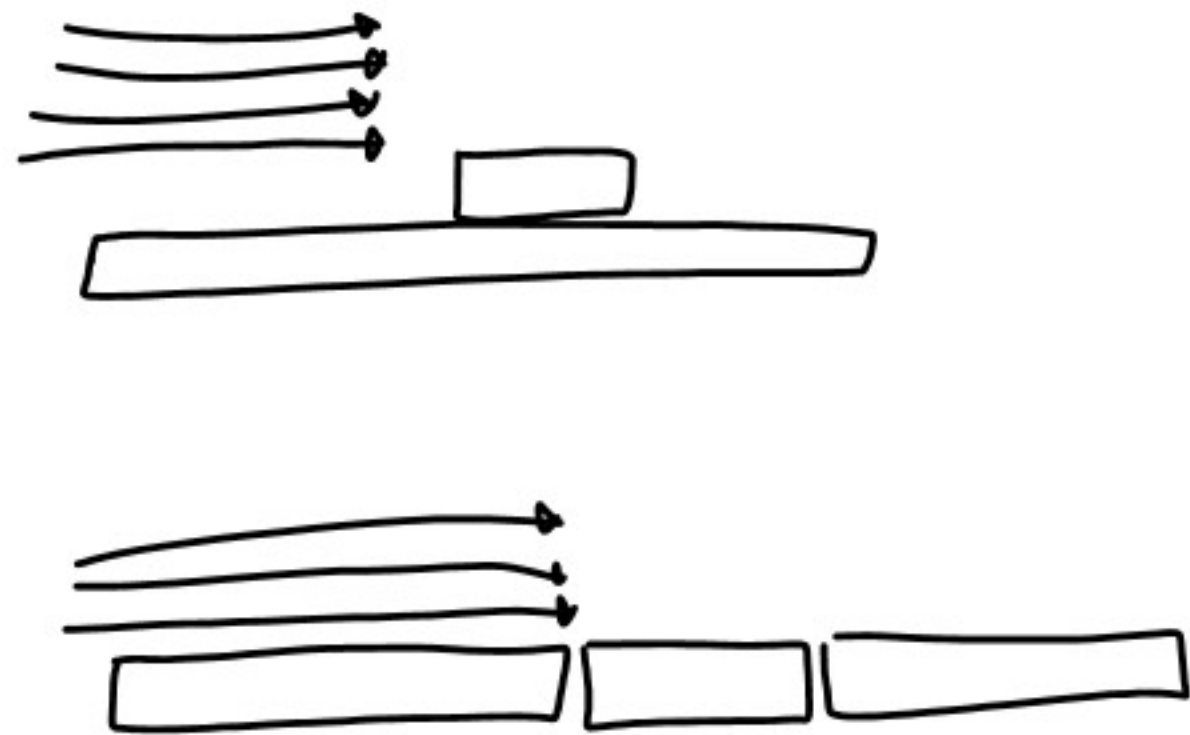
$$= 2.56 \frac{\text{m}^2 \text{K}}{\text{W}}$$

$$q'' = \frac{T_{s_o} - T_{s_i}}{R_{\text{tot}}''} = \frac{22^\circ\text{C} - (-6^\circ\text{C})}{2.56 \frac{\text{m}^2 \text{K}}{\text{W}}} = 10.9 \frac{\text{W}}{\text{m}^2}$$

$$A_s = 3 \text{ m} \cdot 3 \text{ m} \cdot 6 = 54 \text{ m}^2$$

$$q = A_s q'' = 54 \text{ m}^2 \cdot 10.9 \frac{\text{W}}{\text{m}^2} = \boxed{590 \text{ W}}$$

7.33 A square (10 mm \times 10 mm) silicon chip is insulated on one side and cooled on the opposite side by atmospheric air in parallel flow at $u_\infty = 20$ m/s and $T_\infty = 24^\circ\text{C}$. When in use, electrical power dissipation within the chip maintains a uniform heat flux at the cooled surface. If the chip temperature may not exceed 80°C at any point on its surface, what is the maximum allowable power? What is the maximum allowable power if the chip is flush mounted in a substrate that provides for an unheated starting length of 20 mm?



$$q = A_s q'' \quad A_s = (10 \text{ mm})^2 = (0.01 \text{ m})^2 = 1 \times 10^{-4} \text{ m}^2$$

$$q'' = \bar{h} (T_s - T_\infty) = \bar{h} (80^\circ\text{C} - 24^\circ\text{C}) = \bar{h} 56 \text{ K}$$

$$q = \bar{h} 1 \times 10^{-4} \text{ m}^2 56 \text{ K} = \bar{h} 56 \times 10^{-4} \text{ m}^2 \text{ K}$$

$$T_f = \frac{24 + 80}{2} = 52^\circ\text{C} \approx 325 \text{ K}$$